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# HSM2838C

Silicon Epitaxial Planar Diode for High Speed Switching

# HITACHI

ADE-208-029B (Z)  
Rev. 2

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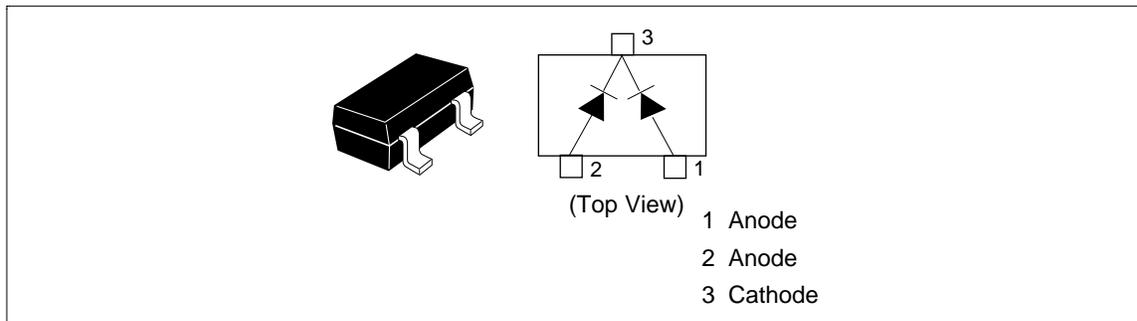
## Features

- Fast recovery time.
- MPAK package is suitable for high density surface mounting and high speed assembly.

## Ordering Information

Type No.	Laser Mark	Package Code
HSM2838C	A6	MPAK

## Pin Arrangement



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## HSM2838C

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### Absolute Maximum Ratings\*<sup>2</sup> (Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V <sub>RM</sub>	85	V
Reverse voltage	V <sub>R</sub>	80	V
Peak forward current	I <sub>FM</sub>	300	mA
Non-Repetitive peak forward surge current	I <sub>FSM</sub> * <sup>1</sup>	4	A
Average forward current	I <sub>O</sub>	100	mA
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

Notes: 1. Within 1μs forward surge current.  
2. Per one device

### Electrical Characteristics\* (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V <sub>F1</sub>	—	0.76	1.0	V	I <sub>F</sub> = 10mA
	V <sub>F2</sub>	—	0.88	1.0		I <sub>F</sub> = 50mA
	V <sub>F3</sub>	—	0.97	1.2		I <sub>F</sub> = 100mA
Reverse current	I <sub>R</sub>	—	—	0.1	μA	V <sub>R</sub> = 80V
Capacitance	C	—	0.5	2.0	pF	V <sub>R</sub> = 0V, f = 1MHz
Reverse recovery time	t <sub>rr</sub>	—	—	3.0	ns	I <sub>F</sub> = 10mA, V <sub>R</sub> = 6V, R <sub>L</sub> = 50Ω

Note: Per one device

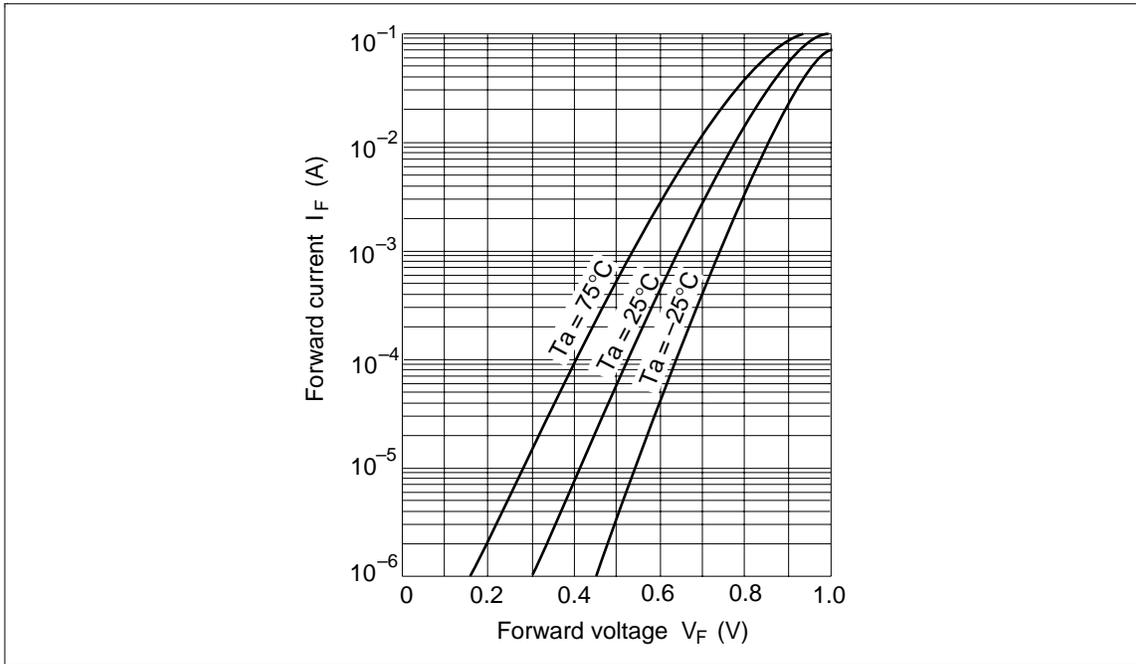


Fig.1 Forward current Vs. Forward voltage

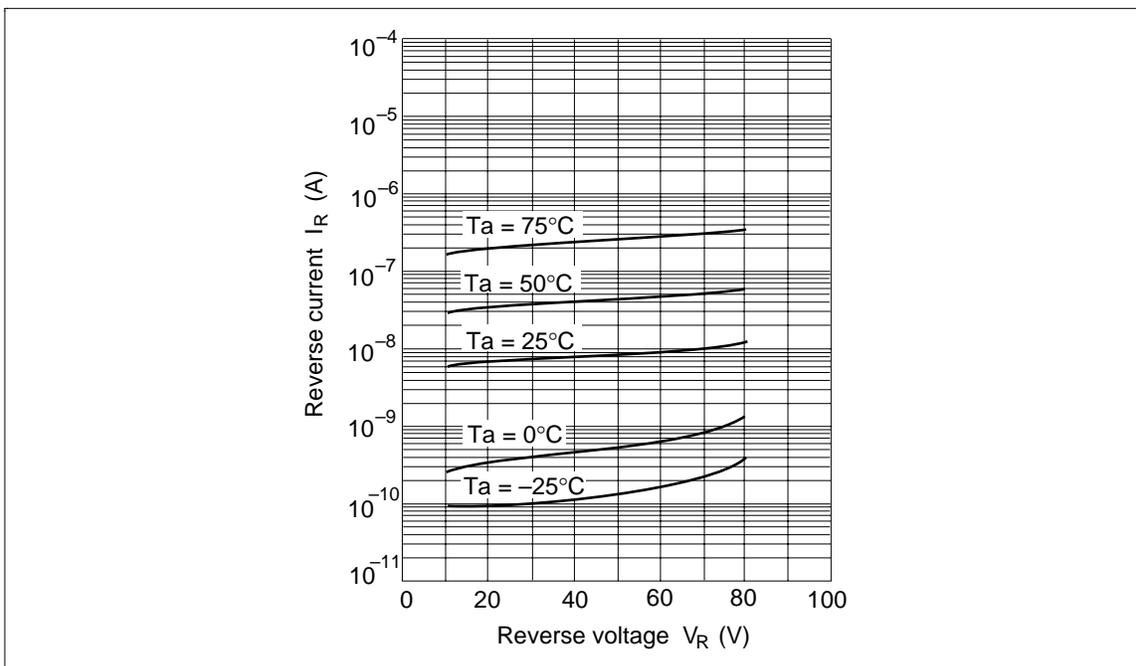


Fig.2 Reverse current Vs. Reverse voltage

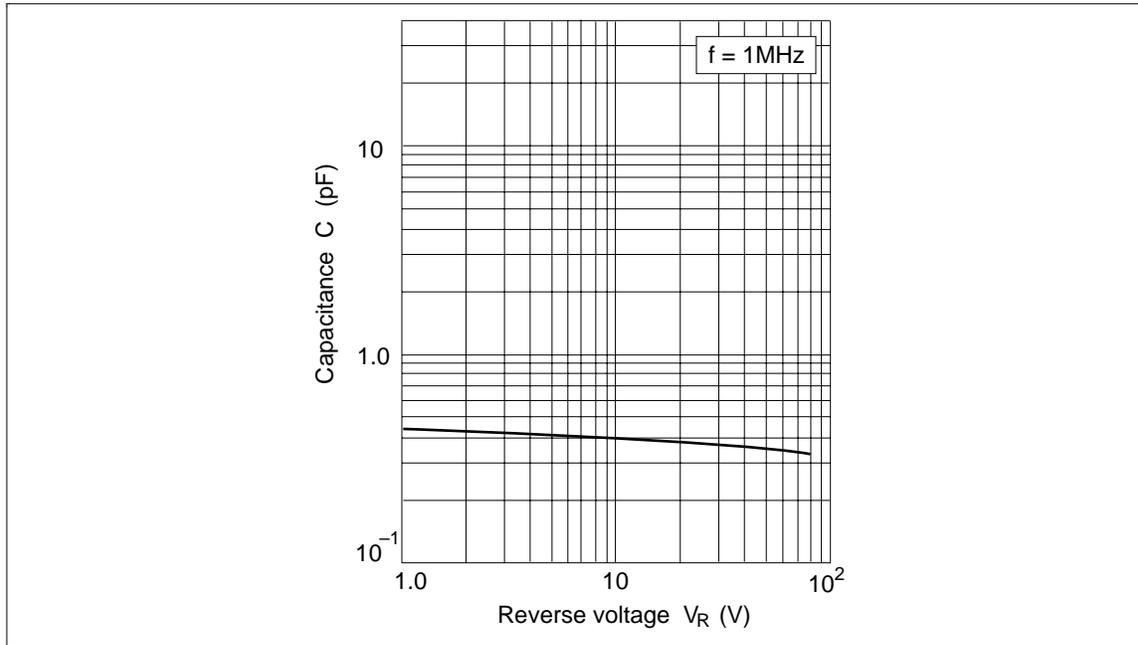


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

